DESCRIPTION

~~HEAT-RESISTANT ADHESIVE SHEET FOR SEMICONDUCTOR INSPECTION~~

Technical field

[0001]

The present invention relates to a heat-resistant adhesive sheet for semiconductor testing.

Background art

[0002]

A semiconductor chip can be produced in the following manner. First, a circuit pattern is formed on a semiconductor wafer and an adhesive sheet is bonded to the semiconductor wafer, and then, the semiconductor wafer undergoes the following steps: cutting the wafer into chips (dicing step); washing and drying the sheet; expanding the sheet (expansion step); peeling the chips off from the sheet (pick-up step); and mounting the chips. It is required that the adhesive sheet such as a dicing tape used in those steps has a sufficient adhesive force to adhere the diced chips from the dicing step to the drying step, while reducing such adhesive force in the pick-up step to such an extent that adhesive deposit does not occur.

[0003]

There has been known an adhesive sheet formed by applying an adhesive layer which will be cured by polymerization with ultraviolet light and so forth, to a base material having a

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